

A Metallic Interconnect for Intermediate Temperature Planar, Solid Oxide Fuel Cells (SOFC)

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- Develop coatings for metallic interconnects Outline a methodology for selecting interconnect materials Alloys and coatings Develop oxidation kinetics models for coatings Deposit coatings on metallic interconnects Electron beam vaporization Sputtering Solution techniques Phase assemblage Electrical conductivit
- Oxidation kinetics Test Interconnects in Planar SOFC stacks

Desired oxide coating deposited directly on interconnect Decrease oxidation rate Increase electronic conductivity

Coating reacts with naturally occurring oxide (Cr₂O₂) Resulting phase exhibits better electronic conductivity Resulting phase suppresses oxidation kinetics Resulting phase suppresses volatilization of chromium

Protective Coatings

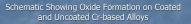
Directly deposit desired coating Perovskites: Sr doped LaMnO_3, Sr doped LaCrO_3 Spinels: Mn_2_xCr_1_*xO_4 ($0 \le x \le 1$)

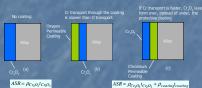
- A₂BO,
- (Mn, Co)₃O₄ LSM Perovskite
- on techniques tron Beam Vapor Deposition

Two-Probe Resistance Measurement



ires: 200 to 800 °C res: Air and Hydrogen, Dry and Wet

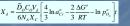




Oxidation Model

 $\frac{9\tilde{D}_{\odot}C_{\odot}X_{c}}{2\tilde{D}_{\circ}C}X_{d} = \frac{3V_{c}\tilde{D}_{\odot}C_{\odot}}{4N}\left[\frac{4}{3}\ln a_{\odot}^{*} - \frac{2}{3}\frac{\Delta G^{*}}{PT} - \ln p_{0}^{*}\right]$



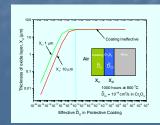


Oxidation kinetics are linear, similar to interface-controlled Oxidation rate determined by oxide ion diffusivity in coating



Oxidation kinetics are parabolic, similar to diffusion-controlled Oxidation rate dictated by Cr diffusivity in formed oxide layer

Illustrative Calculation of Coating Effectiveness



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Deposition of oxide coatings by sputtering

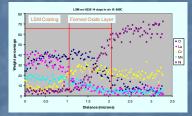
Ni, Cr superalloy 56% Ni, 26% Cr, 0.75% Mn, 5.3% Co, 4.8% W, Fe, Mo, Oxide Layer Formation: Cr₂O₃, (Mn, Cr)₃O₄ spinel

RF, 200 W, Argon La_{0.85}Sr_{0.15}MnO₃₋₆ Mn₂CrO₄ Thickness of 1.3 µm

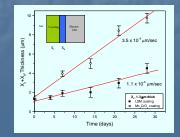
Sputtered LSM coating on Haynes 230 Oxidized for 14 days at 800 °C in air



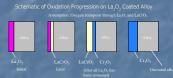
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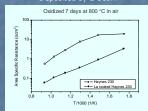


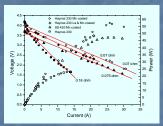
Haynes 230 oxidized in air @ 800 °C











- Developed oxidation models for both protective and consumptive coatings Two limiting cases of oxidation: 1) linear (coating limited) 2) parabolic (diffusion limited by oxide formation on alloy) Depasted protective coatings on metallic interconnects Perovskires and Min-based Spinels
- Oxidation kinetics exhibits linear behavior and is dictated by oxide ion diffusivity in the protective coating
- Consumptive coatings promote the formation of Spinel and Perovskite phases that exhibit higher electronic conductivity than the native oxide
- The area specific resistance of oxidized Ni-Cr alloys was reduced by over an order of magnitude with coatings

Acknowledgements

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